TOSHIBA CMOS Integrated Circuit Silicon Monolithic

TCA62746FG,TCA62746FNG

16-Output Constant Current LED Driver with Output Open/Short Detection

The TCA62746 series are LED drivers with sink type constant circuit output, making them ideal for controlling LED modules and displays.

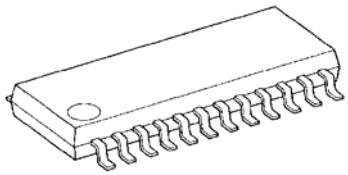
The current value of the 16-output is configurable using one external resistor.

In addition, these drivers are equipped with a function for detecting the output voltage when the output load LEDs open or short, and which then outputs the result as serial data.

These drivers consist of a 16-constant current output block, a 16-bit shift register, a 16-bit latch and a 16-bit AND-gate.

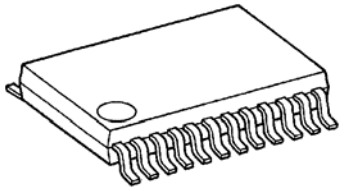
The suffix (G) appended to the part number represents a Lead (Pb)-Free product.

TCA62746FG



SSOP24-P-300-1.00B

TCA62746FNG



SSOP24-P-300-0.65A

Weight
SSOP24-P-300-1.00B : 0.32 g (typ.)
SSOP24-P-300-0.65A : 0.14 g (typ.)

Features

- 16-output built-in
- Output open detection (OOD) function
  : When in detection mode, outputs the detection results via SOUT.
- Output short detection (OSD) function
  : When in detection mode, outputs the detection results via SOUT.
- Output current setting range
  : 2 to 50 mA × 16-constant current output
- Current accuracy (@ R_{EXT} = 1.56 kΩ, V_O = 1.0 V, V_{DD} = 5.0 V)
  : Between outputs: ± 1% (typ.)
  Between devices: ± 3% (typ.)
- Control data format: serial-in, parallel-out
- I/O logic: TTL level (Schmitt trigger input)
- Data transfer frequency: f_{MAX} = 25 MHz
- Power supply voltage: V_{DD} = 4.5 to 5.5 V
- Operation temperature range: T_{opr} = −40 to 85°C
- LED supply voltage: $V_{O(OFF)}$ = 16 V (max)
- Output delay circuit built-in: Internal data reset circuit for power-on resetting (POR)
- Backward compatible to TB62706B and TB62726A series drivers
- Package: FG type: SSOP24-P-300-1.00B
  FNG type: SSOP24-P-300-0.65A

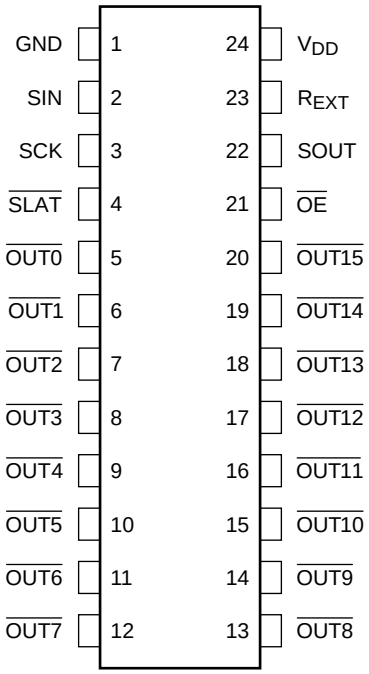
Caution

This device is sensitive to electrostatic discharge. Please handle with care.
The terminals which are marginal to electro static discharge are shown in the following table.
(Please refer to page 18 for details.)

ESD condition	Marginal terminals
MM (±200V)	5,6,7,8,9,10,11,12,13,14,15,16,19,20

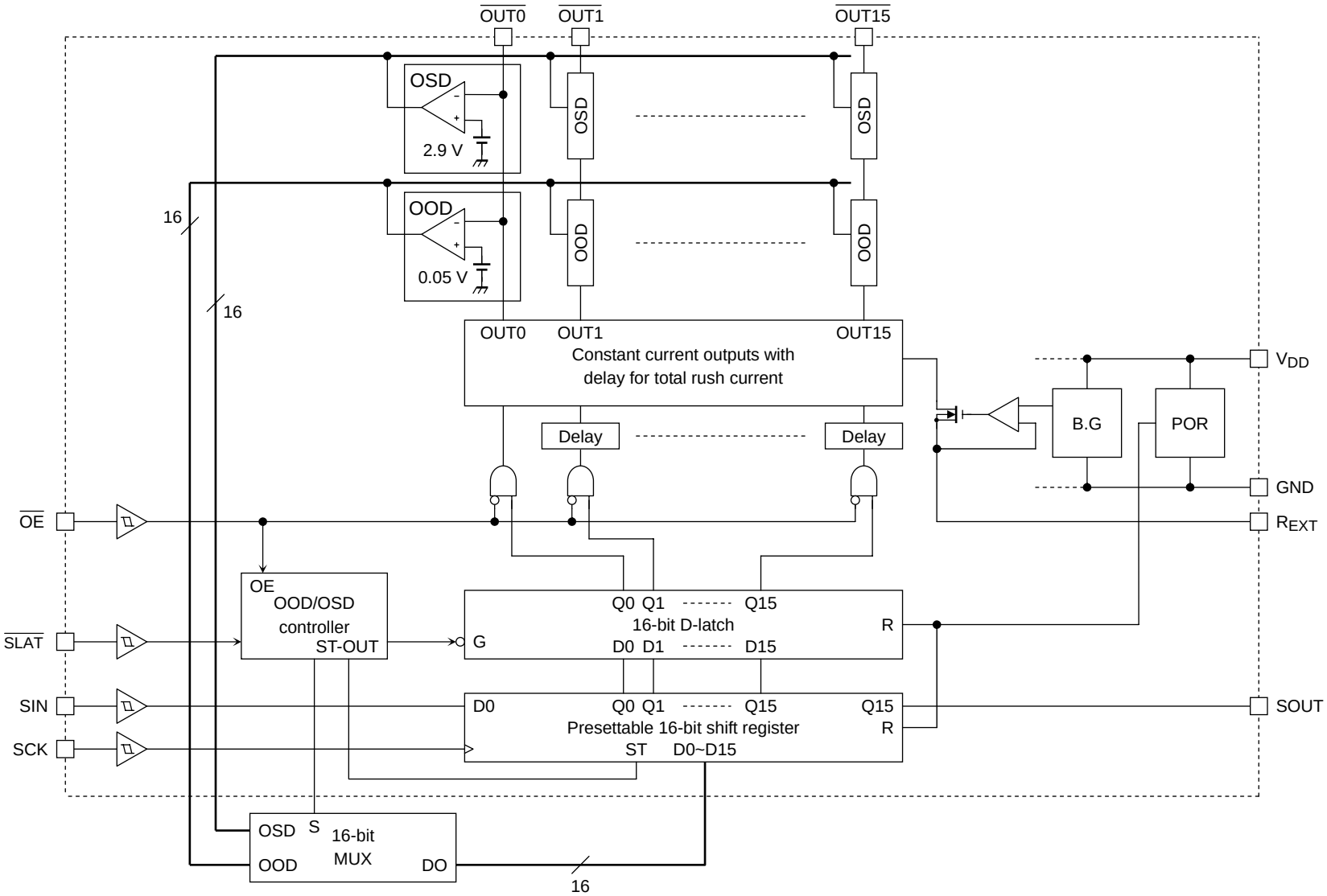
Pin Assignment (top view)

As shown below, this series has the same pin assignments as the TB62706B and TB62726A series:



Note: Short circuiting an output pin to a power supply pin (V_{DD} or V_{LED}), or short-circuiting the R_{EXT} pin to the GND pin will likely exceed the rating, which in turn may result in smoldering and/or permanent damage. Please keep this in mind when determining the wiring layout for the power supply and GND pins.

Block Diagram

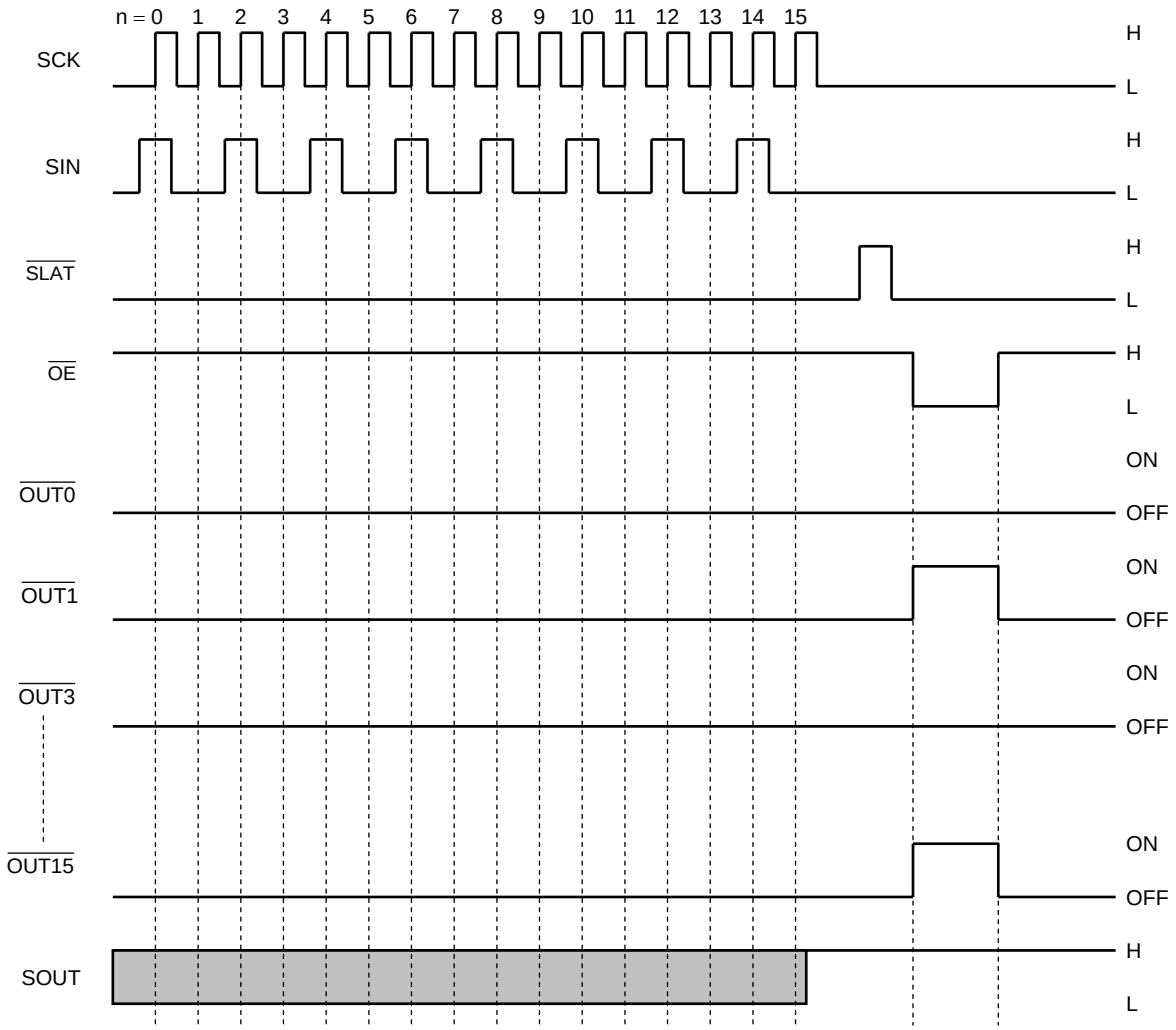


Truth Table

SCK	$\overline{SLAT}$	$\overline{OE}$	SIN	$\overline{OUT0}$ ⋯ $\overline{OUT7}$ ⋯ $\overline{OUT15}$	SOUT
↑	H	L	Dn	Dn ⋯ Dn – 7 ⋯ Dn – 15	Dn – 15
↑	L	L	Dn + 1	No Change	Dn – 14
↑	H	L	Dn + 2	Dn + 2 ⋯ Dn – 5 ⋯ Dn – 13	Dn – 13
↓	X	L	Dn + 3	Dn + 2 ⋯ Dn – 5 ⋯ Dn – 13	Dn – 13
↓	X	H	Dn + 3	OFF	Dn – 13

Notes: When $\overline{OUT0}$ to $\overline{OUT15}$ output pins are set to "H" the respective output will be ON and when set to "L" the respective output will be OFF.
In order to ensure proper operations, an external resistor must be connected between the R-EXT and GND pins and the logic power and a Toshiba-recommended capacitor should be connected between the VDD and GND pins.

Timing Chart



Note 1: The latch circuit is a leveled-latch circuit. Please exercise precaution as it is not triggered-latch circuit.

Note 2: Keep the $\overline{SLAT}$ pin is set to “L” to enable the latch circuit to hold data. In addition, when the $\overline{SLAT}$ pin is set to “H” the latch circuit does not hold data. The data will instead pass onto output.
When the $\overline{OE}$ pin is set to “L” the $\overline{OUT0}$ to $\overline{OUT15}$ output pins will go ON and OFF in response to the data. In addition, when the $\overline{OE}$ pin is set to “H” all the output pins will be forced OFF regardless of the data.

Pin Functions

Pin No	Pin Name	I/O	Function
1	GND	—	The ground pin.
2	SIN	I	The serial data input pin.
3	SCK	I	The serial data transfer clock input pin.
4	$\overline{SLAT}$	I	The parallel data save (latch) signal input pin. When the “L” level is constant, it is saved as parallel data. Also used for OOD/OSD mode settings.
5	$\overline{OUT0}$	O	A sink type constant current output pin.
6	$\overline{OUT1}$	O	A sink type constant current output pin.
7	$\overline{OUT2}$	O	A sink type constant current output pin.
8	$\overline{OUT3}$	O	A sink type constant current output pin.
9	$\overline{OUT4}$	O	A sink type constant current output pin.
10	$\overline{OUT5}$	O	A sink type constant current output pin.
11	$\overline{OUT6}$	O	A sink type constant current output pin.
12	$\overline{OUT7}$	O	A sink type constant current output pin.
13	$\overline{OUT8}$	O	A sink type constant current output pin.
14	$\overline{OUT9}$	O	A sink type constant current output pin.
15	$\overline{OUT10}$	O	A sink type constant current output pin.
16	$\overline{OUT11}$	O	A sink type constant current output pin.
17	$\overline{OUT12}$	O	A sink type constant current output pin.
18	$\overline{OUT13}$	O	A sink type constant current output pin.
19	$\overline{OUT14}$	O	A sink type constant current output pin.
20	$\overline{OUT15}$	O	A sink type constant current output pin.
21	$\overline{OE}$	I	The output force off signal input pin. During the “H” level, the output will be forced off regardless of whether the parallel data is “H” or “L”. Also used for OOD/OSD mode settings.
22	SOUT	O	The serial data output pin. This pin outputs the LED ON data and OOD/OSD detection result data.
23	R_{EXT}	O	The constant current value setting resistor connection pin.
24	V_{DD}		The logic power supply input pin.

Absolute Maximum Ratings (T_{opr} = 25°C)

Characteristics	Symbol	Rating	Unit
Power supply voltage	V_{DD}	−0.4 to 6	V
Output current	I_O	55	mA
Logic input voltage	V_{IN}	−0.4 to V_{DD} + 0.4 *2	V
Constant current output voltage	V_O	−0.4 to 17	V
Operating temperature	T_{opr}	−40 to 85	°C
Storage temperature	T_{stg}	−55 to 150	°C
Saturation heat-resistance of junction to ambient	$R_{th(j-a)}$	94 (When mounted PCB) / 120 (When mounted PCB)	°C/W
Power dissipation	P_D	1.32 (When mounted PCB) / 1.04 (When mounted PCB) *3	W

Note1: Voltage is ground referenced.
Note2: However, do not exceed 6V.
Note3: The power dissipation decreases the reciprocal of the saturated thermal resistance (1/n) for each degree (1°C) that the ambient temperature is exceeded (Ta = 25°C).
Note3: PCB condition (76.2 x 114.3 x 1.6 mm, Cu 30%)

DC Items

Recommended Operating Conditions (Unless otherwise specified, Topr = −40°C to 85°C)

Characteristics	Symbol	Test Conditions	Min	Typ.	Max	Unit
Power supply voltage	V_{DD}	—	4.5	—	5.5	V
Output voltage when OFF	$V_{O\ (OFF)}$	$\overline{OUT0}$ to $\overline{OUT15}$	—	—	16	V
Output voltage when ON	$V_{O\ (ON)}$	$\overline{OUT0}$ to $\overline{OUT15}$	0.7	—	4	V
High level logic input voltage	V_{IH}	—	2.0	—	V_{DD}	V
Low level logic input voltage	V_{IL}	—	GND	—	0.8	V
High level logic output current	I_{OH}	V_{DD} = 5 V@SOUT	—	—	−1	mA
Low level logic output current	I_{OL}	V_{DD} = 5 V@SOUT	—	—	1	mA
Constant current output	I_O	$\overline{OUT0}$ to $\overline{OUT15}$	2	—	50	mA
Operating temperature	T_{opr}	—	−40	—	85	V

AC Items during Normal Operations

Recommended Operating Conditions
(Unless otherwise specified, V_{DD} = 4.5 to 5.5 V and T_{opr} = −40°C to 85°C)

Characteristics	Symbol	Test Conditions	Min	Typ.	Max	Unit
Serial data transfer frequency	f_{SCK}	—	—	—	25	MHz
Clock pulse width	$t_{pw\ (SCK)}$	SCK = “H” or “L”	20	—	—	ns
Latch pulse width	$t_{pw\ (SLAT)}$	$\overline{SLAT}$ = “H”	20	—	—	ns
Enable pulse width	$t_{pw\ (OE)}$	$\overline{OE}$ = “H” or “L”	100	—	—	ns
Serial data setup time	t_S	SIN-SCK (↑), SCK (↑) − $\overline{SLAT}$ (↓)	5	—	—	ns
Serial data hold time	t_H	SCK (↑) − SIN, $\overline{SLAT}$ (↓) − SCK (↑)	5	—	—	ns

Electrical Characteristics (Unless otherwise specified, V_{DD} = 4.5 to 5.5 V and Topr = 25°C)

Characteristics	Symbol	Test Conditions	Min	Typ.	Max	Unit
Power supply voltage	V_{DD}	—	4.5	5.0	5.5	V
Output voltage	V_O	—	—	—	16	V
Output current	I_O	—	2	—	50	mA
High level logic output voltage	V_{OH}	I_{OH} = −1 mA, SOUT	V_{DD} − 0.4	—	—	V
Low level logic output voltage	V_{OL}	I_{OH} = +1 mA, SOUT	—	—	0.4	V
High level logic input current	I_{IH}	V_{IN} = V_{DD}, $\overline{OE}$, SIN, SCK	—	—	1	μA
Low level logic input current	I_{IL}	V_{IN} = GND, $\overline{SLAT}$, SIN, SCK	—	—	−1	μA
Power supply current 1	I_{DD1}	V_O = 16 V, No R_{EXT} SCK = "L", $\overline{OE}$ = "H"	—	0.1	0.5	mA
Power supply current 2	I_{DD2}	V_O = 1.0 V, R_{EXT} = 1.56 kΩ, All output OFF	—	—	7.0	mA
Power supply current 3	I_{DD3}	V_O = 1.0 V, R_{EXT} = 500 Ω, All output OFF	—	—	14.0	mA
Power supply current 4	I_{DD4}	V_O = 1.0 V, R_{EXT} = 1.2 kΩ, All output ON	—	—	7.0	mA
Power supply current 5	I_{DD5}	V_O = 1.0 V, R_{EXT} = 500 Ω, All output ON	—	—	14.0	mA
Constant current output 1	I_{O1}	V_{DD} = 5.0V, V_O = 1.0 V, R_{EXT} = 1.56 kΩ, All output ON	14.1	15	15.9	mA
Constant current output 2	I_{O2}	V_{DD} = 5.0V, V_O = 1.0 V, R_{EXT} = 500 Ω, All output ON	44.2	47	49.8	mA
Output OFF leak current	I_{OK}	V_O = 16 V, R_{EXT} = 1.56 kΩ, All output OFF	—	—	0.5	μA
Constant current error	ΔI_O	V_{DD} = 5.0V, V_O = 1.0 V, R_{EXT} = 1.56 kΩ, $\overline{OUT0}$ to $\overline{OUT15}$	—	±1	±3	%
Constant current power supply voltage regulation	$\%V_{DD}$	V_{DD} = 4.5 to 5.5V, V_O = 1.0 V, R_{EXT} = 1.56 kΩ, $\overline{OUT0}$ to $\overline{OUT15}$	—	±1	±4	%/V
Constant current output voltage regulation	$\%V_O$	V_{DD} = 5.0V, V_O = 1.0 to 3.0 V, R_{EXT} =.56 kΩ, $\overline{OUT0}$ to $\overline{OUT15}$	—	±1	±4	%/V
Pull-up resistor	R_{UP}	$\overline{OE}$	250	500	800	kΩ
Pull-down resistor	R_{DOWN}	$\overline{SLAT}$	250	500	800	kΩ

Electrical Characteristics during OOD/OSD Mode (Unless otherwise specified, V_{DD} = 4.5 to 5.5 V and Topr = 25°C)

Characteristics	Symbol	Test Conditions	Min	Typ.	Max	Unit
OOD voltage	V_{OOD}	V_{DD} = 4.5 to 5.5 V	—	0.05	—	V
OSD voltage	V_{OSD}	V_{DD} = 4.5 to 5.5 V	—	2.9	—	V

Switching Characteristics (Unless otherwise specified, T_{opr} = 25°C and V_{DD} = 5.0 V)

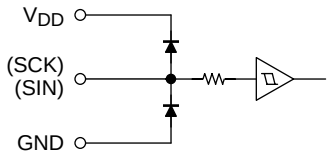
Characteristics		Symbol	Test Conditions (Note 1)	Min	Typ.	Max	Unit
Propagation delay time	SCK- $\overline{OUT0}$	t_{pLH1}	$\overline{SLAT}$ = "H", $\overline{OE}$ = "L"	—	20	100	ns
	$\overline{SLAT}$ - $\overline{OUT0}$	t_{pLH2}	$\overline{OE}$ = "L"	—	20	100	
	$\overline{OE}$ - $\overline{OUT0}$	t_{pLH3}	$\overline{SLAT}$ = "H"	—	20	100	
	SCK-SOUT	t_{pLH}	—	5	10	—	
	SCK- $\overline{OUT0}$	t_{pHL1}	$\overline{SLAT}$ = "H", $\overline{OE}$ = "L"	—	50	100	
	$\overline{SLAT}$ - $\overline{OUT0}$	t_{pHL2}	$\overline{OE}$ = "L"	—	50	100	
	$\overline{OE}$ - $\overline{OUT0}$	t_{pHL3}	$\overline{SLAT}$ = "H"	—	50	100	
	SCK-SOUT	t_{pHL}	—	15	20	—	
Pulse width	SCK	t_{wSCK}	—	20	—	—	ns
	$\overline{SLAT}$	t_{wSLAT}	—	20	—	—	
	$\overline{OE}$	t_{wOE1}	—	100	—	—	
	$\overline{OE}$	t_{wOE2}	—	2	—	—	μs
Hold time		t_{HOLD1}	—	5	—	—	ns
		t_{HOLD2}	—	10	—	—	
		t_{HOLD3}	—	10	—	—	
Setup time		t_{SETUP1}	—	5	—	—	ns
		t_{SETUP2}	—	5	—	—	
		t_{SETUP3}	—	10	—	—	
		t_{SETUP4}	—	10	—	—	
Maximum clock rise time		t_r	(Note 2)	—	—	500	ns
Maximum clock fall time		t_f	(Note 2)	—	—	500	ns
Output rise time		t_{or}	10 to 90% of voltage waveform	—	30	150	ns
Output fall time		t_{of}	90 to 10% of voltage waveform	—	70	150	ns
Output delay time		$t_{DLY\ (ON)}$	$\overline{OUTn}$ - $\overline{OUT}$ (n + 1) between adjacent outputs	—	20	—	ns
Output delay time		$t_{DLY\ (OFF)}$	$\overline{OUTn}$ - $\overline{OUT}$ (n + 1) between adjacent outputs	—	20	—	ns

Note 1: T_{opr} = 25°C, V_{DD} = V_{IH} = 5.0 V, V_{OUT} = 1.0 V, V_{IL} = 0 V, R_{EXT} = 500 Ω, I_{OUT} = 47 mA, V_L = 5.0 V, C_L = 10.5 pF (Refer to Test Circuit.)

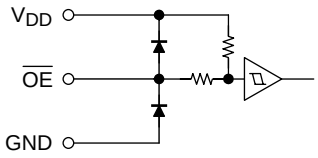
Note 2: If the device is connected in a cascade and the tr/tf of the clock waveform increases due to deceleration of the clock waveform, it may not be possible to achieve the timing required for data transfer. Please keep these timing conditions in mind when designing your application.

I/O Equivalent Circuits

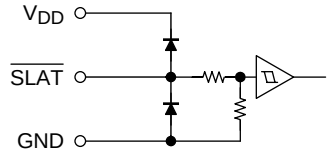
1. SCK, SIN (No pull-up or pull-down resistors)



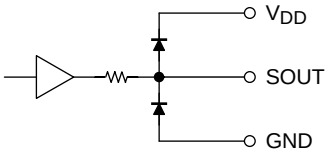
2. $\overline{OE}$ (Pull-up resistor)



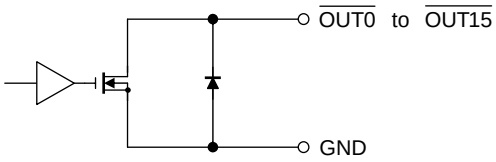
3. $\overline{SLAT}$ (Pull-down resistor)



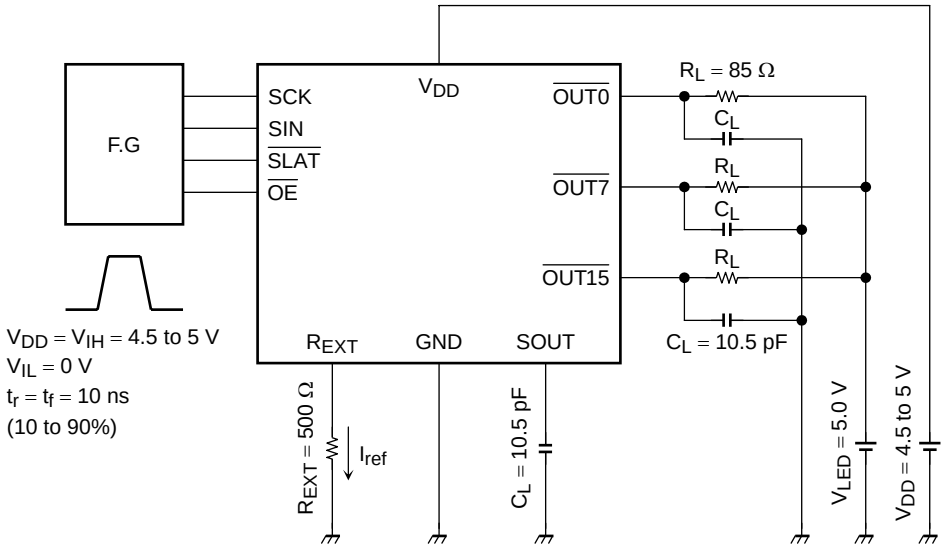
4. SOUT



5. $\overline{OUT0}$ to $\overline{OUT15}$



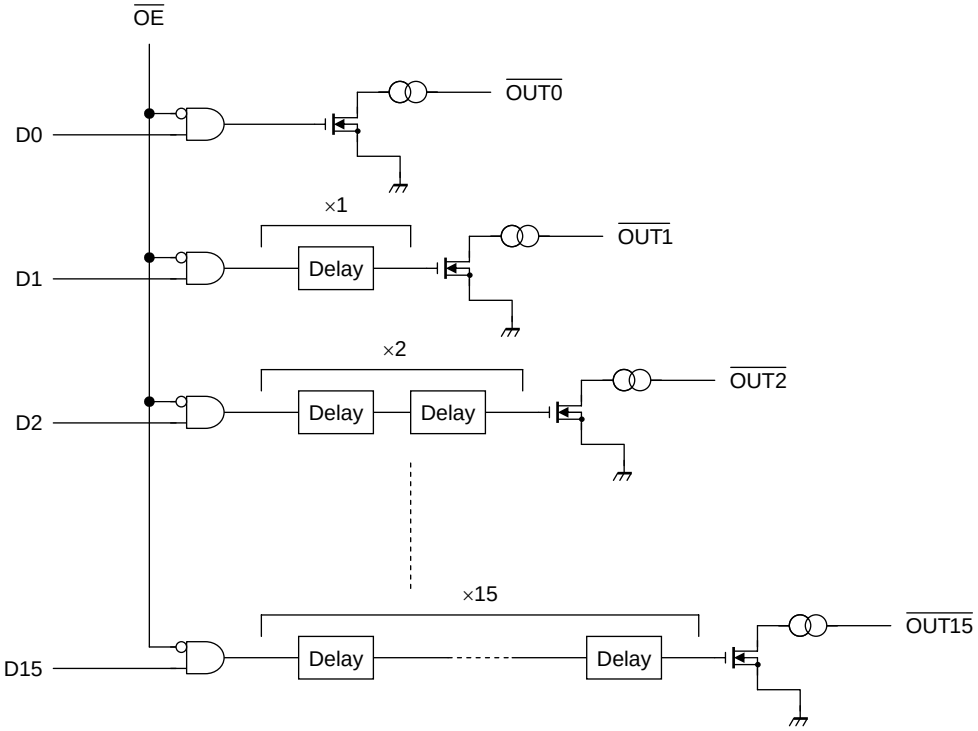
Test Circuit



Output Delay Circuit

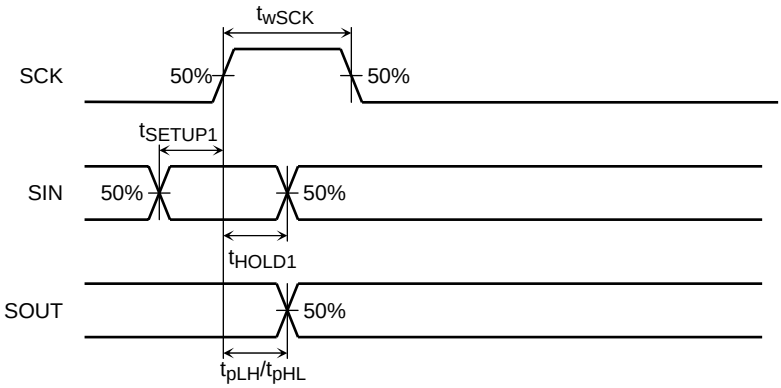
A delay circuit is built-in to each output, with the equivalent as illustrated below.

There is a switching time lag (20 ns typ.) between adjacent outputs. This is designed for high speed switching between outputs and is intended to have the effect of reducing switching noise by reducing the di/dt when all outputs are ON or OFF at the same time.

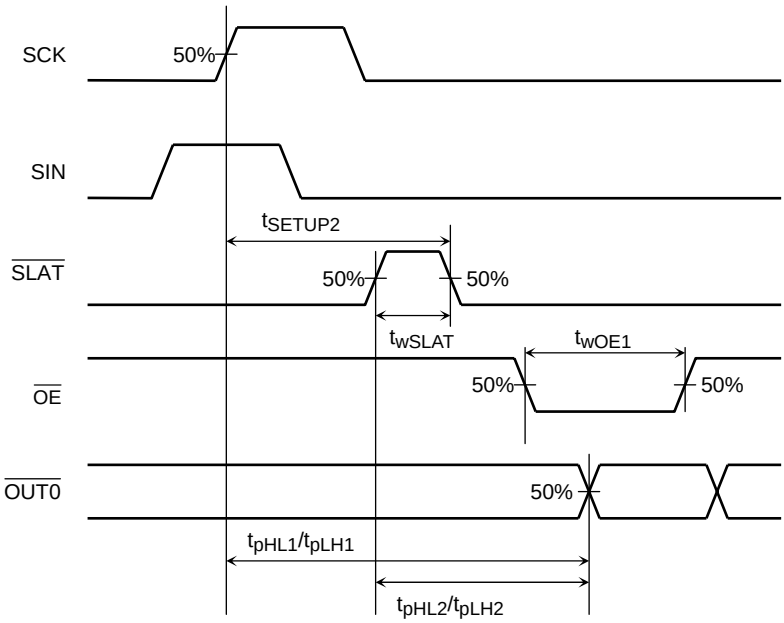


Timing Waveforms

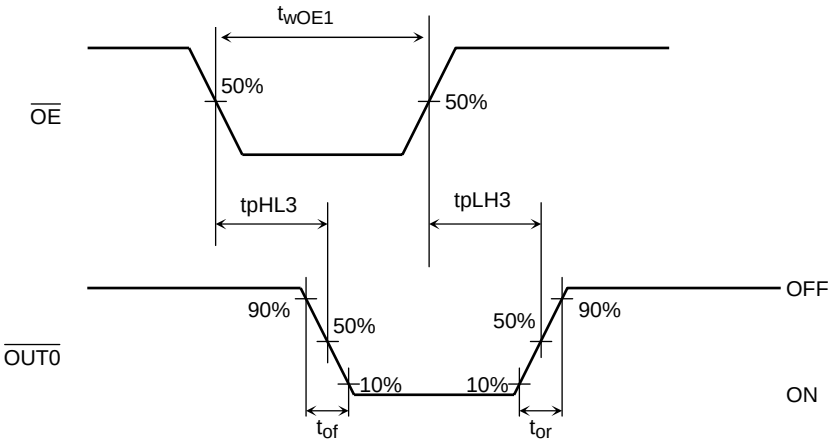
1. SCK, SIN, SOUT



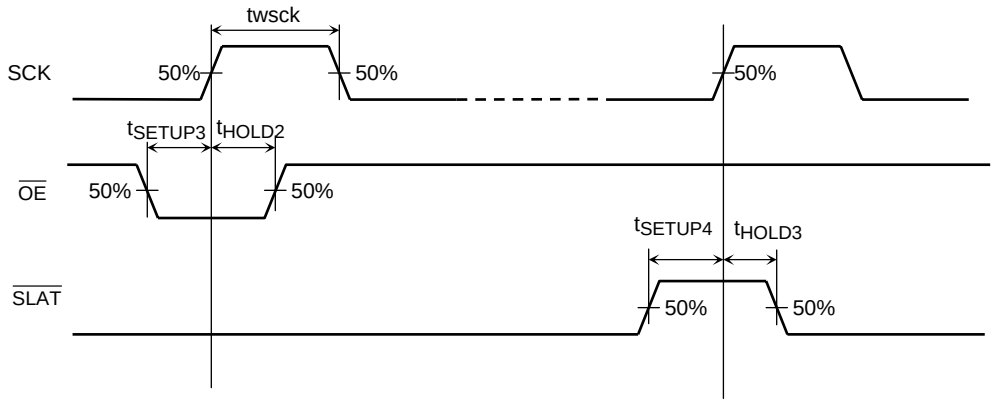
2. SCK, SIN, $\overline{\text{SLAT}}$, $\overline{\text{OE}}$, $\overline{\text{OUT0}}$



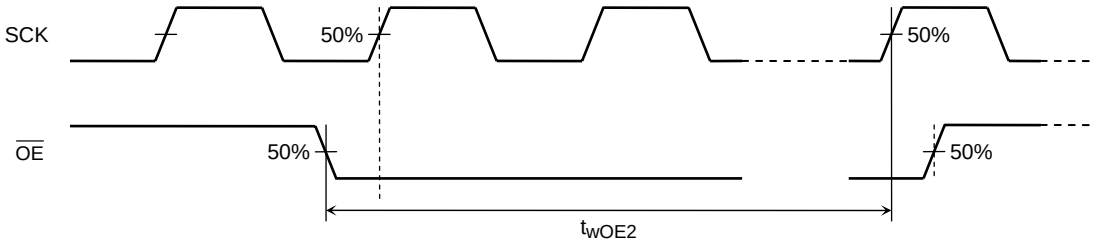
3. $\overline{\text{OUT0}}$



4. OOD Mode/OSD Mode

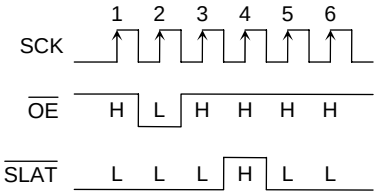


5. OOD/OSD Read Mode



Switching to Open Circuit Detection (OOD) and Short Circuit Detection (OSD) Modes

Switching to OSD mode

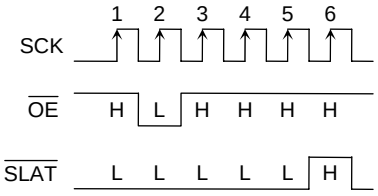


The signal sequence sets TCA62746 to be in the OSD mode. Here, the $\overline{SLAT}$ active pulse would not latch any data.

Description

As shown in the above figures, once a short pulse "HLHHH" of $\overline{OE}$ appears, TCA62746 would go thorough the mode switching. At the fourth rising edge of SCK, if $\overline{SLAT}$ is sampled as "H", TCA62746 would switch to the OSD mode; otherwise, it would switch to the Normal Mode.

Switching to OOD mode

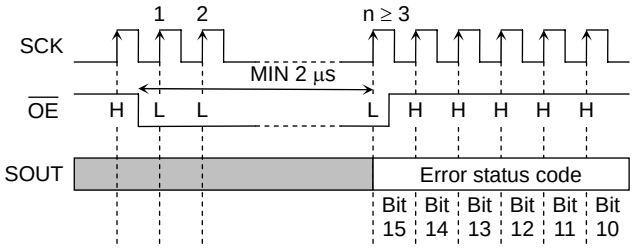


The signal sequence sets TCA62746 to be in the OOD mode. Here, the $\overline{SLAT}$ active pulse would not latch any data.

Description

As shown in the above figures, once a short pulse "HLHHHH" of $\overline{OE}$ appears, TCA62746 would go thorough the mode switching. At the sixth rising edge of SCK, if $\overline{SLAT}$ is sampled as "H", TCA62746 would switch to the OOD mode; otherwise, it would switch to the Normal Mode.

Reading Error Status Code

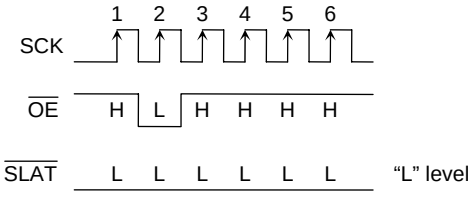


When TCA62746 is working under the OOD and OSD modes, the above sequence signals can enable a system controller to read Error Status codes through SOUT pin.

Description

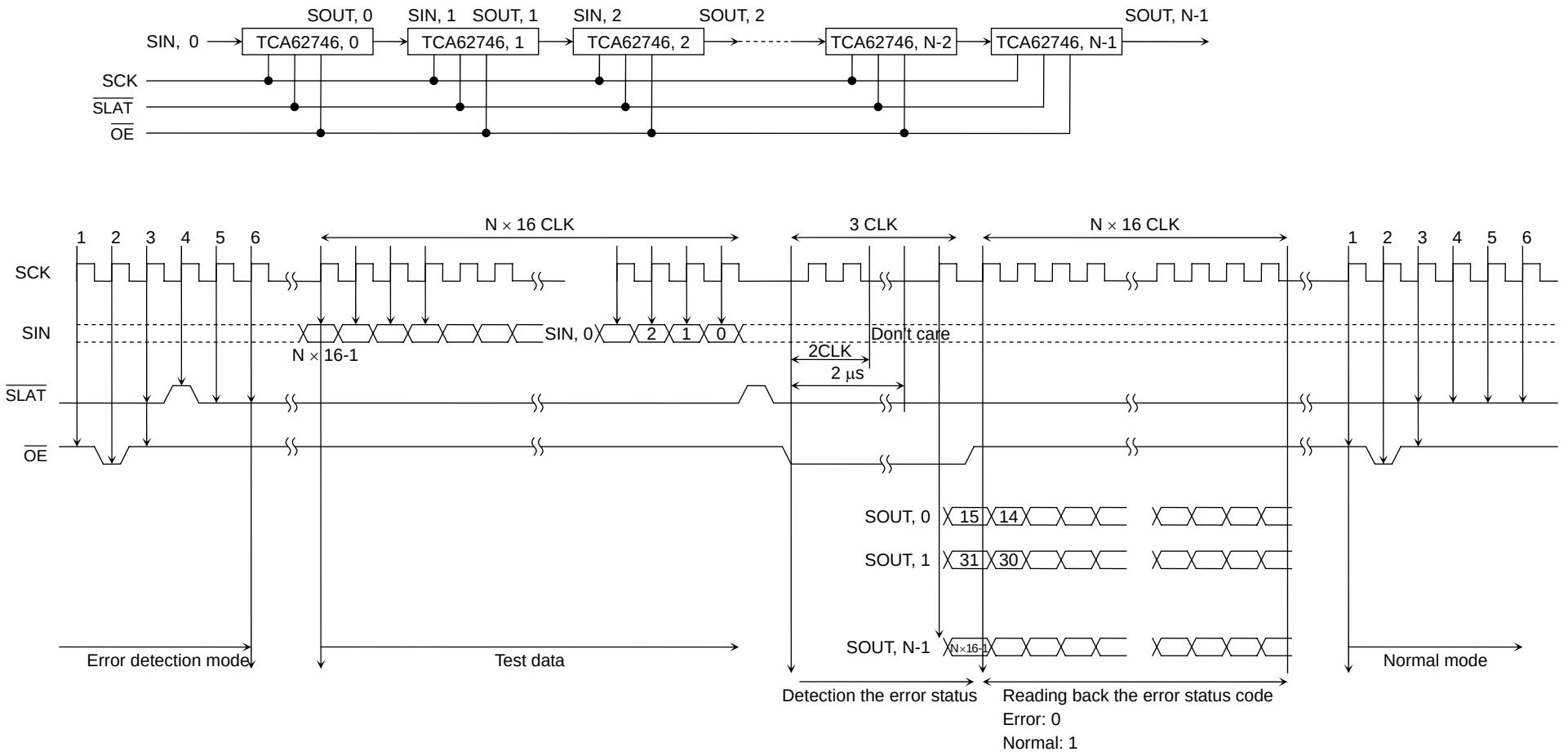
In the OOD and OSD modes, the state of $\overline{OE}$ must be switched from "H" to "L". And, then, TCA62746 would execute Open-/Short-circuit Detection as well as enabling output ports to drive current. At least three "L" must be sampled at the "L" state of $\overline{OE}$ and the last "L" should be at least 2 μs after the falling edge of $\overline{OE}$. The occurrence of the last "L" results in the event that TCA62746 saves the detected error status into the built-in shift register. Thus, when $\overline{OE}$ is at the voltage low state, the serial data cannot be shifted into TCA62746 through SIN pin. The "L" and "1" shown in the above figure is sampled at the rising edge of each SCK. Before reading the Error Status Code, the state of $\overline{OE}$ should be pulled up to "H" from "L", the output ports are closed and the detection is finished. Then, the error status saved in the built-in register would be shifted out through SOUT pin bit by bit by sending SCK.

Switching to Normal Mode



The signal sequence sets TCA62746 to be in the Normal mode.

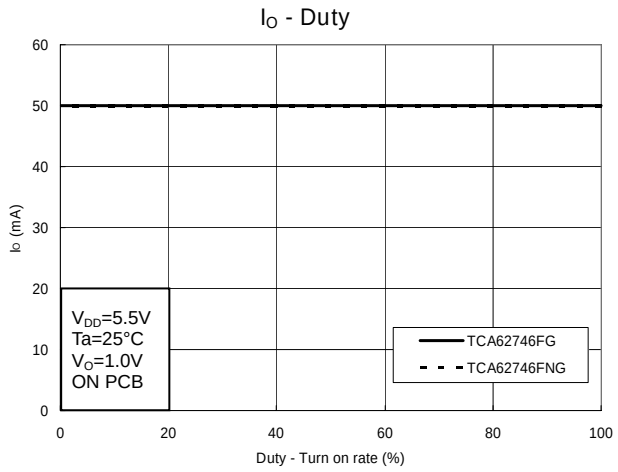
Timing chart of Error detection mode (An example)

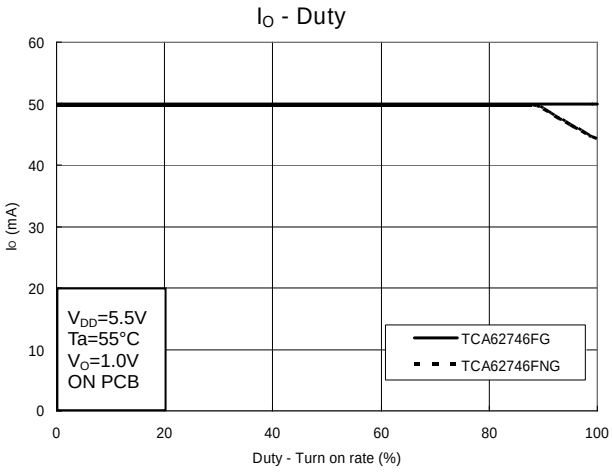


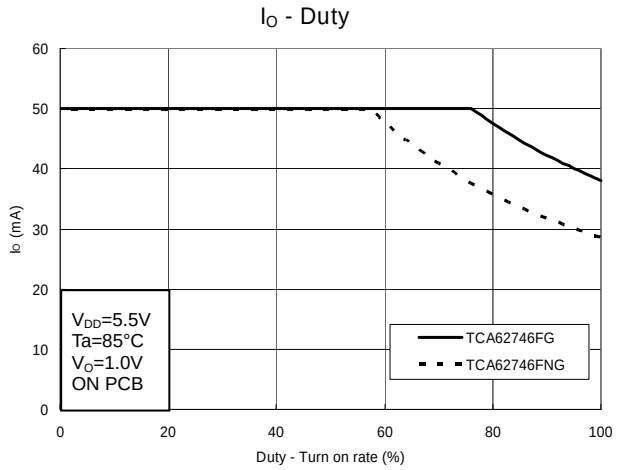
Reference data

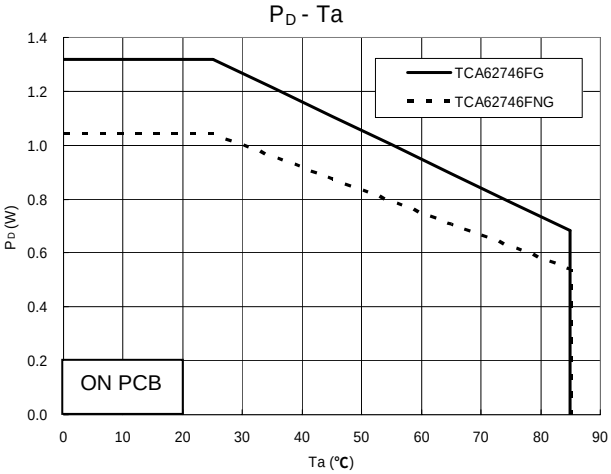
*This data is a reference value, and no guarantee value.

Output Current – Duty (LEDS turn-on rate)

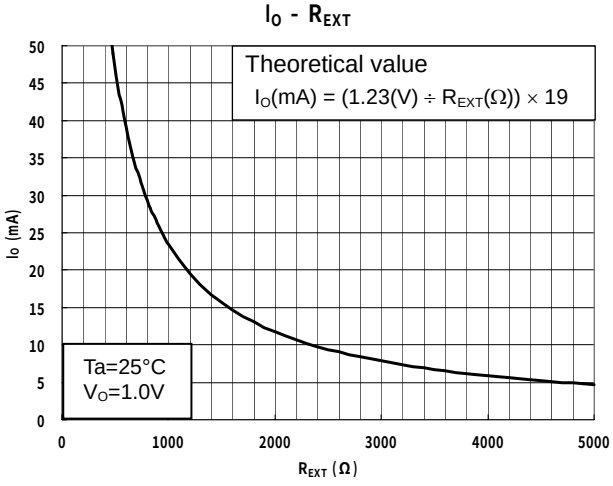






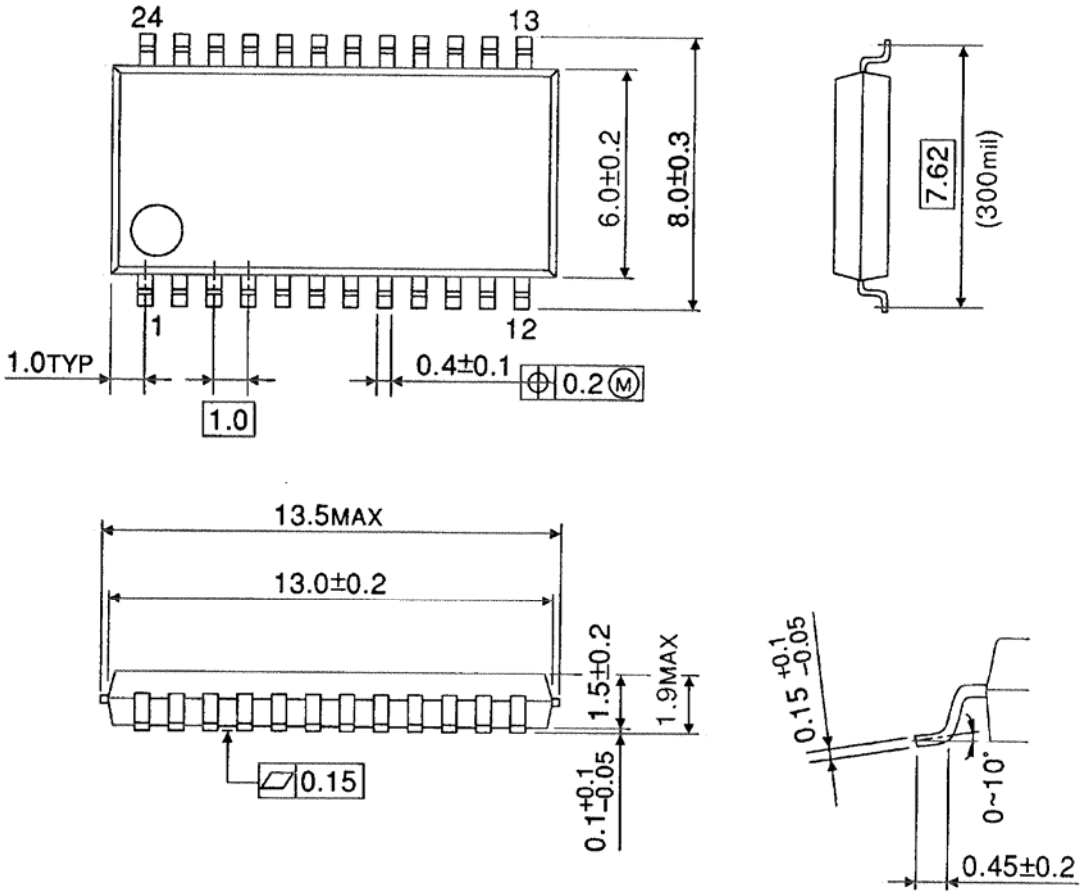


Output Current – R_{EXT} Resistor



Package Dimensions

SSOP24-P-300-1.00B Unit : mm

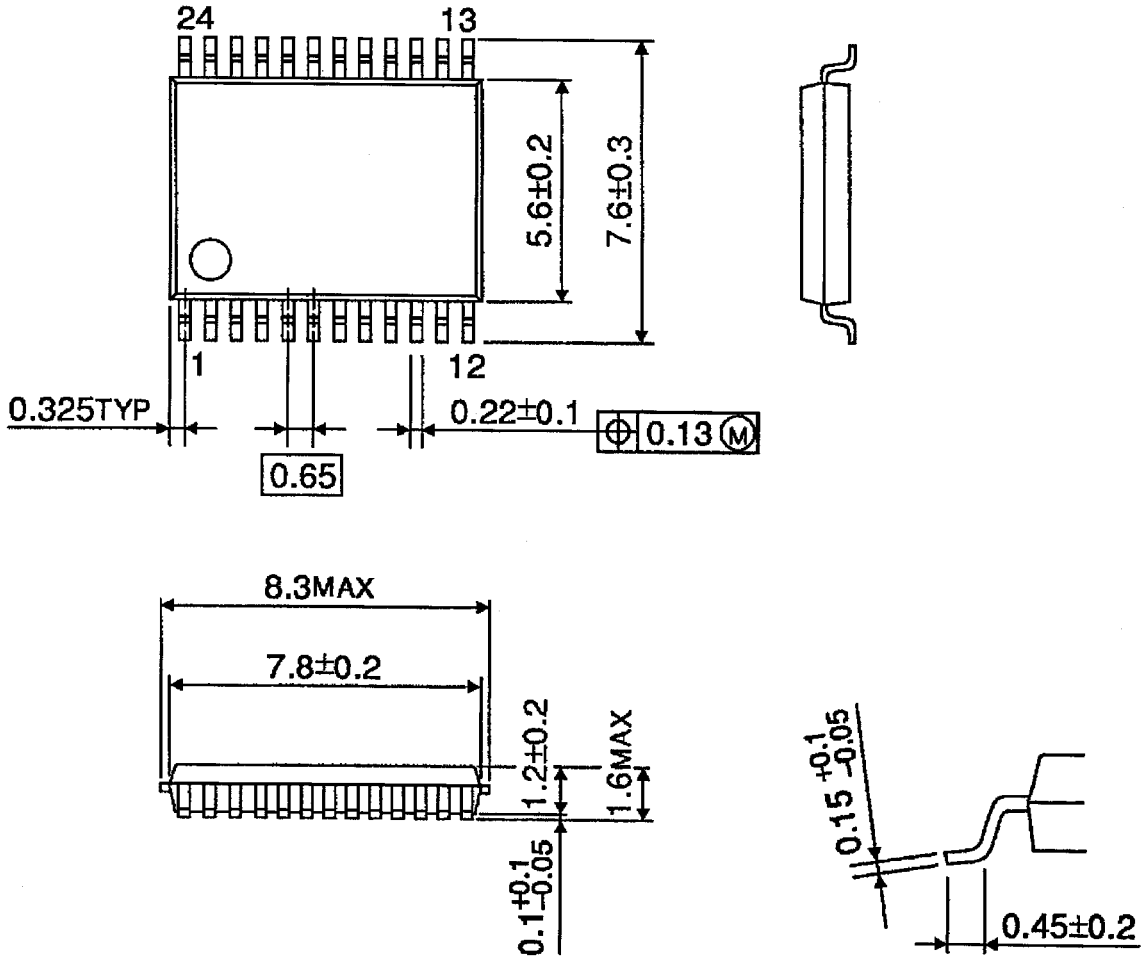


Weight: 0.32 g (typ.)

Package Dimensions

SSOP24-P-300-0.65A

単位 : mm



Weight: 0.14 g (typ.)

Serge resisting

The terminals which are weak to electro static discharge are shown in the following table.

pin	ESD test : MM(±200V)					
	- Serge			+ Serge		
	Standard	NG	OK	Standard	NG	OK
1	V_{DD}	—	200	V_{DD}	—	200
2	V_{DD},GND	—	200	V_{DD},GND	—	200
3	V_{DD},GND	—	200	V_{DD},GND	—	200
4	V_{DD},GND	—	200	V_{DD},GND	—	200
5	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
6	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
7	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
8	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
9	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
10	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
11	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
12	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
13	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
14	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
15	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
16	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
17	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
18	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
19	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
20	V_{DD},GND	—	200	V_{DD},GND	**180**	**160**
21	V_{DD},GND	—	200	V_{DD},GND	—	200
22	V_{DD},GND	—	200	V_{DD},GND	—	200
23	V_{DD},GND	—	200	V_{DD},GND	—	200
24	GND	—	200	GND	—	200

Notes on Contents

1. Block Diagrams

Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes.

2. Equivalent Circuits

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

3. Timing Charts

Timing charts may be simplified for explanatory purposes.

4. Application Circuits

The application circuits shown in this document are provided for reference purposes only. Thorough evaluation is required, especially at the mass production design stage.

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5. Test Circuits

Components in the test circuits are used only to obtain and confirm the device characteristics. These components and circuits are not guaranteed to prevent malfunction or failure from occurring in the application equipment.

IC Usage Considerations

Notes on handling of ICs

[1] The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings.
Exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.

[2] Use an appropriate power supply fuse to ensure that a large current does not continuously flow in case of over current and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow and the breakdown can lead smoke or ignition. To minimize the effects of the flow of a large current in case of breakdown, appropriate settings, such as fuse capacity, fusing time and insertion circuit location, are required.

[3] If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. IC breakdown may cause injury, smoke or ignition.
Use a stable power supply with ICs with built-in protection functions. If the power supply is unstable, the protection function may not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.

[4] Do not insert devices in the wrong orientation or incorrectly.
Make sure that the positive and negative terminals of power supplies are connected properly.
Otherwise, the current or power consumption may exceed the absolute maximum rating, and exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.
In addition, do not use any device that is applied the current with inserting in the wrong orientation or incorrectly even just one time.

[5] Carefully select external components (such as inputs and negative feedback capacitors) and load components (such as speakers), for example, power amp and regulator.
If there is a large amount of leakage current such as input or negative feedback condenser, the IC output DC voltage will increase. If this output voltage is connected to a speaker with low input withstand voltage, overcurrent or IC failure can cause smoke or ignition. (The over current can cause smoke or ignition from the IC itself.) In particular, please pay attention when using a Bridge Tied Load (BTL) connection type IC that inputs output DC voltage to a speaker directly.

About solderability, following conditions were confirmed

- Solderability

  (1) Use of Sn-37Pb solder Bath
  - solder bath temperature = 230°C
  - dipping time = 5 seconds
  - the number of times = once
  - use of R-type flux

  (2) Use of Sn-3.0Ag-0.5Cu solder Bath
  - solder bath temperature = 245°C
  - dipping time = 5 seconds
  - the number of times = once
  - use of R-type flux

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